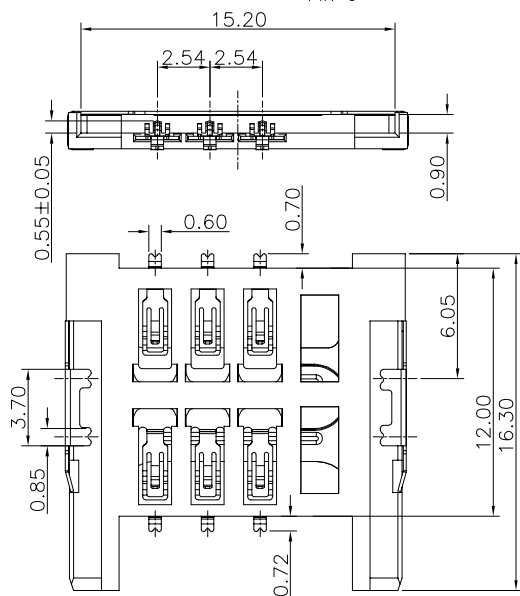
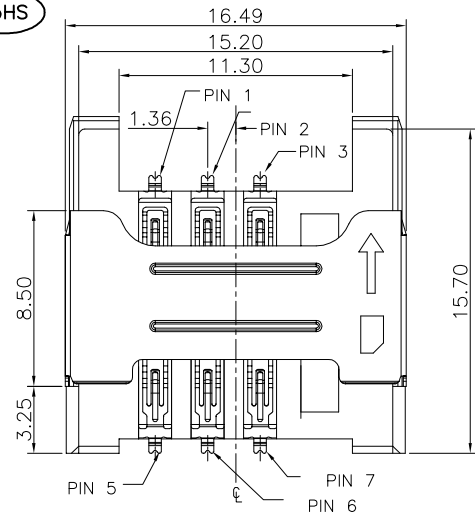
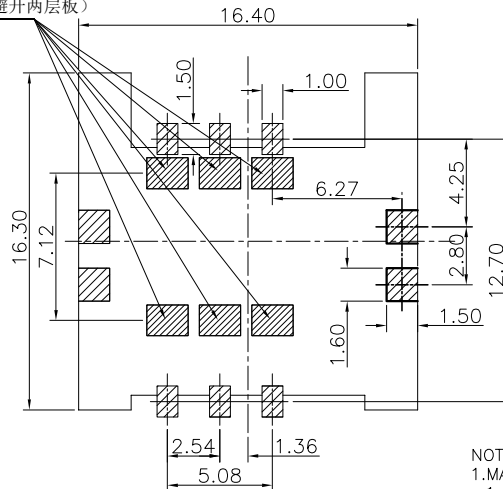


The product using material and processing must conform to the "WI-PZ-001"HSF technical standard control requirements

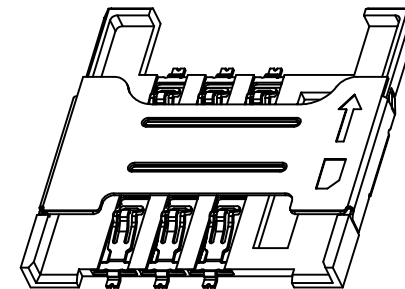
RoHS



禁布区域：此区域内为端子头部下压区域，区域内不可有任何线路及钢箔（至少避开两层板）



RECOMMENDED PCB LAYOUT TOLERANCE: ±0.05



NOTE:

1.MATERIAL SPECIFICATION:

- 1-1.HOUSING:LCP UL94 V-0
- 1-2.CONTACTS:COPPER ALLOY.
- 1-3.SHELL:SUS201

2.PLATING SPECIFICATION:

- 2-1.CONTACTS: SELECTIVE GOLD PLATED ON CONTACT AREA
100u" Min. TIN PLATED ON SOLDER TAIL
50u" Min. NICKEL UNDER-PLATED

2-2. SHELL:

Ni 50u" MIN. UNDER PLATED, GOLD PLATING ON CONTACT AREA

3.ELECTRICAL PERFORMANCE:

- 3-1.CURRENT RATING:0.5A
- 3-2.VOLTAGE RATING:12V MAX
- 3-3.CONTACT RESISTANCE: 50m Ohm MAX.
- 3-4.INSULATION RESISTANCE: 100MQ MIN 100V DC
- 3-5.DIELECTRIC WITHSTANDING VOLTAGE: 100V AC MIN.

4.ENVIRONMENTAL PERFORMANCE:

OPERATING TEMPERATURE: -20°C~+85°C.

WLSMF9-06 2 X X 0 001

PLATING: COLOUR:
1-G/F A:Black
2-AU 3U"
5-AU 15U"
6-AU 30U"

PIN NO.	PIN NAME
PIN 1	Supply Voltage Vcc
PIN 2	Resrt(RST)
PIN 3	Clock (CLK)
PIN 5	Ground
PIN 6	Programming Voltage Vpp
PIN 7	I/O
PIN 4/8	N/A

REV.	REVISION RECORD	DATE	GENERAL TOLERANCES	SCALE:	NAME	DATE	PART.NO:	DWG.NO:
A0	NEW RELEASE	21.01.13	LINEAR	1:1	Wang_jr	21.01.13	WLSMF9-062XX0001	ENDE05
			ANGLES		Ding_bo	21.01.13		
			0.0±0.35		Ou_jian	21.01.13		
			0.00±0.25				TITLE:	
			0.000±0.10				SIM CARD 1.8H 连桥带挡防溃PIN	



REV: A0 SHEET: 1/1